



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Ohtani et al
 Serial No.: 08/690,747
 Filed : August 1, 1996
 Title : METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

Art Unit : 1765
 Examiner : Robert Kunemund

Commissioner for Patents
 Washington, D.C. 20231

AMENDMENT

In response to the action mailed February 15, 2000, please amend the application as follows:

In the Claims:

Please amend claims 1, 6, 22, 23, 26, 27, and 28 as follows:

1. (Amended) A method for manufacturing a semiconductor device comprising the steps of:

forming a non-single crystalline semiconductor film [to become at least a channel forming region] on an insulating surface;

patterning said semiconductor film into a patterned semiconductor film having peripheral portions;

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit

Signature

Sandy Malec

Typed or Printed Name of Person Signing Certificate

07/27/2000 EHANNOND 00000111 08690747

01 FC:102
 02 FC:103
 03 FC:116

234.00 DP
 360.00 DP
 380.00 DP